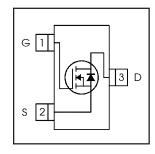


HEXFET® Power MOSFET

V <sub>DS</sub>	30	V
V <sub>GS Max</sub>	± 12	٧
<b>R</b> <sub>DS(on) max</sub> (@V <sub>GS</sub> = 4.5V)	29	$\mathbf{m}\Omega$
<b>R</b> <sub>DS(on) max</sub> (@V <sub>GS</sub> = 2.5V)	37	$\mathbf{m}\Omega$





#### Application(s)

• Load/ System Switch

#### **Features and Benefits**

Low $R_{DSon}$ (<29m $\Omega$ )
Industry-standard SOT-23 Package
RoHS compliant containing no lead, no bromide and no halogen
MSL1, Consumer Qualification

results in

# Benefits Lower Conduction Losses Multi-vendor compatibility Environmentally friendly Increased Reliability

**Absolute Maximum Ratings** 

Symbol Parameter		Max.	Units
V <sub>DS</sub>	Drain-Source Voltage	30	V
I <sub>D</sub> @ T <sub>A</sub> = 25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V	5.0	
I <sub>D</sub> @ T <sub>A</sub> = 70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V	4.0	А
I <sub>DM</sub>	Pulsed Drain Current	25	
P <sub>D</sub> @T <sub>A</sub> = 25°C	Maximum Power Dissipation	1.3	10/
P <sub>D</sub> @T <sub>A</sub> = 70°C Maximum Power Dissipation		0.8	<del> </del> w
	Linear Derating Factor	0.01	W/°C
V <sub>GS</sub> Gate-to-Source Voltage		± 12	V
T <sub>J,</sub> T <sub>STG</sub> Junction and Storage Temperature Range		-55 to + 150	°C

#### **Thermal Resistance**

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JA}$	Junction-to-Ambient ③		100	°C/W
$R_{\theta JA}$	Junction-to-Ambient (t<10s) @		99	0/44

#### ORDERING INFORMATION:

See detailed ordering and shipping information on the last page of this data sheet.

Notes ① through ④ are on page 10 www.irf.com



#### Electric Characteristics @ $T_J = 25$ °C (unless otherwise specified)

Symbol	Parameter	Min.	Тур.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	30			٧	$V_{GS} = 0V, I_{D} = 250\mu A$
	Breakdown Voltage Temp. Coefficient		0.02		V/°C	Reference to 25°C, I <sub>D</sub> = 1mA
<b>D</b>	Static Drain-to-Source On-Resistance		22	29	mΩ	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 5.0A ②
R <sub>DS(on)</sub>	Static Dialit-to-Source Off-Nesistance		27	37	11122	V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 4.0A ②
$V_{GS(th)}$	Gate Threshold Voltage	0.5	0.8	1.1	٧	$V_{DS} = V_{GS}$ , $I_D = 10\mu A$
I <sub>DSS</sub>	Drain-to-Source Leakage Current			1.0	uА	$V_{DS} = 24V, V_{GS} = 0V$
	Diam-to-Source Leakage Current			150	μΑ	$V_{DS} = 24V, V_{GS} = 0V, T_{J} = 125^{\circ}C$
I <sub>GSS</sub>	Gate-to-Source Forward Leakage			100	пA	V <sub>GS</sub> = 12V
	Gate-to-Source Reverse Leakage			-100	I IIA	V <sub>GS</sub> = -12V
$R_G$	Internal Gate Resistance		1.7		Ω	
gfs	Forward Transconductance	19			S	$V_{DS} = 10V, I_{D} = 5.0A$
$Q_g$	Total Gate Charge		6.8			I <sub>D</sub> = 5.0A
$Q_{gs}$	Gate-to-Source Charge		0.3		nC	V <sub>DS</sub> =15V
$Q_{gd}$	Gate-to-Drain ("Miller") Charge		2.4			V <sub>GS</sub> = 4.5V ②
t <sub>d(on)</sub>	Turn-On Delay Time		4.2			V <sub>DD</sub> =15V②
t <sub>r</sub>	Rise Time		5.6			I <sub>D</sub> = 1.0A
t <sub>d(off)</sub>	Turn-Off Delay Time		22		ns	$R_G = 6.8\Omega$
t <sub>f</sub>	Fall Time		9.1			$V_{GS} = 4.5V$
C <sub>iss</sub>	Input Capacitance		650			$V_{GS} = 0V$
C <sub>oss</sub>	Output Capacitance		65		рF	V <sub>DS</sub> = 25V
C <sub>rss</sub>	Reverse Transfer Capacitance		46		Ī	f = 1.0 MHz

#### **Source - Drain Ratings and Characteristics**

Symbol	Parameter	Min.	Тур.	Max.	Units	Conditions
I <sub>S</sub>	Continuous Source Current			1.3		MOSFET symbol
	(Body Diode)			1.0	Α	showing the
I <sub>SM</sub>	Pulsed Source Current			25		integral reverse
	(Body Diode) ①			23		p-n junction diode.
$V_{SD}$	Diode Forward Voltage			1.2	٧	$T_J = 25$ °C, $I_S = 5.0$ A, $V_{GS} = 0$ V ②
t <sub>rr</sub>	Reverse Recovery Time		10	15	ns	$T_J = 25$ °C, $V_R = 15$ V, $I_F = 1.3$ A
Q <sub>rr</sub>	Reverse Recovery Charge		3.8	5.7	nC	di/dt = 100A/µs ②

# International Rectifier

# IRLML6344TRPbF

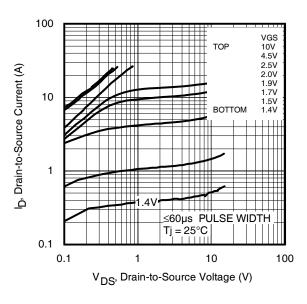


Fig 1. Typical Output Characteristics

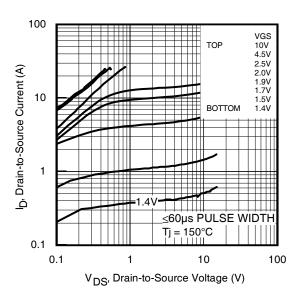


Fig 2. Typical Output Characteristics

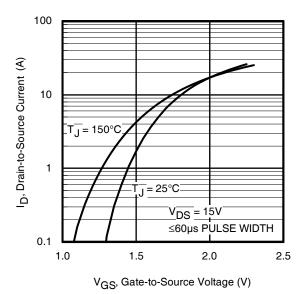
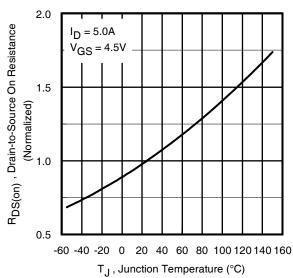
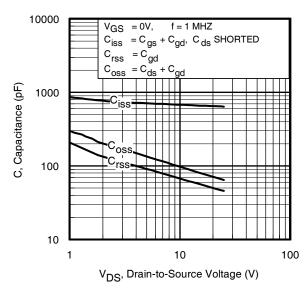


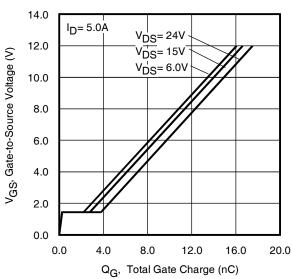
Fig 3. Typical Transfer Characteristics



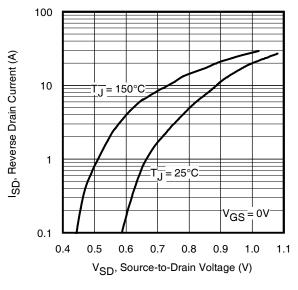
**Fig 4.** Normalized On-Resistance Vs. Temperature



**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage



**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage



**Fig 7.** Typical Source-Drain Diode Forward Voltage

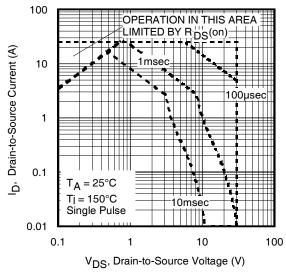
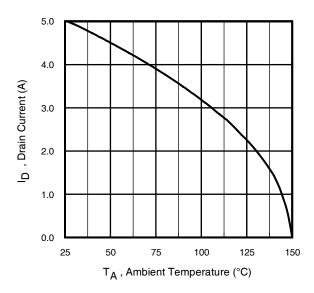


Fig 8. Maximum Safe Operating Area

# International Rectifier

# IRLML6344TRPbF



**Fig 9.** Maximum Drain Current Vs. Ambient Temperature

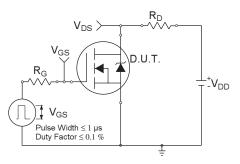


Fig 10a. Switching Time Test Circuit

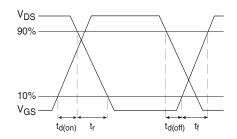


Fig 10b. Switching Time Waveforms

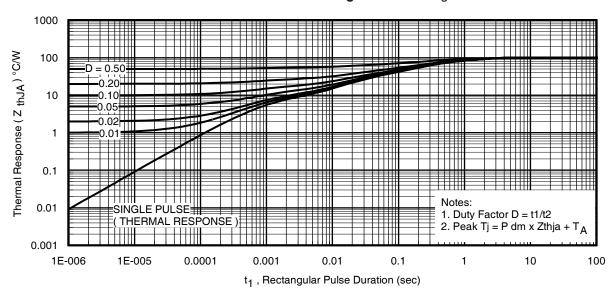
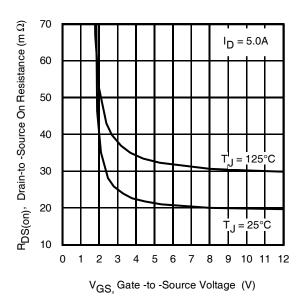


Fig 11. Typical Effective Transient Thermal Impedance, Junction-to-Ambient



(mg), Drain-to-Source On Resistance (mg), Drain-to-Source On Box (ou), Dra

**Fig 12.** Typical On-Resistance Vs. Gate Voltage

Fig 13. Typical On-Resistance Vs. Drain Current

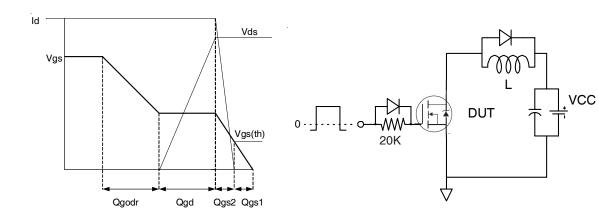
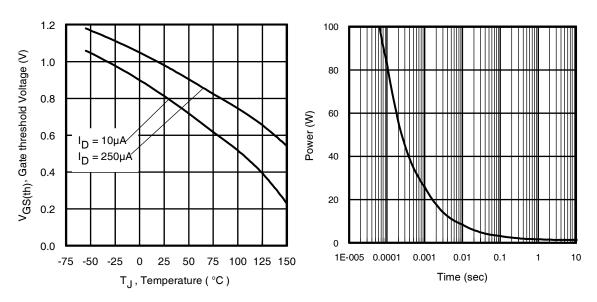


Fig 14a. Basic Gate Charge Waveform

Fig 14b. Gate Charge Test Circuit

# International Rectifier

# IRLML6344TRPbF



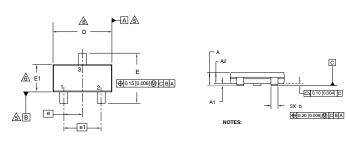
**Fig 15.** Typical Threshold Voltage Vs. Junction Temperature

Fig 16. Typical Power Vs. Time

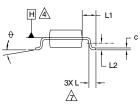


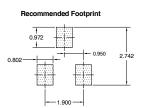
#### Micro3™(SOT-23) Package Outline

Dimensions are shown in millimeters (inches)



DIMENSIONS				
SYMBOL	MILLIMETERS		INCHES	
STIVIBOL	MIN	MAX	MIN	MAX
Α	0.89	1.12	0.035	0.044
A1	0.01	0.10	0.0004	0.004
A2	0.88	1.02	0.035	0.040
b	0.30	0.50	0.012	0.020
С	0.08	0.20	0.003	0.008
D	2.80	3.04	0.110	0.120
Е	2.10	2.64	0.083	0.104
E1	1.20	1.40	0.047	0.055
е	0.95	BSC	0.037	BSC
e1	1.90	BSC	0.075	BSC
L	0.40	0.60	0.016	0.024
L1	0.54	REF	0.021	REF
L2	0.25	BSC	0.010	BSC
0	0	8	0	8





- 1. DIMENSIONING & TOLERANCING PER ANSI Y14.5M-1994
- 1. DIMENSIONING & TOLEPANCING PER ANSI Y14.5M-1994
  2. DIMENSIONS ARE SHOWN IN MULIMETERS (INCHES).
  3. CONTROLLING DIMENSION: MILLIMETER

  ADATUM PLANE HIS LOCATED AT THE MICL PARTITING LINE.

  ADATUM A AND B TO BE DETERMINED AT DATUM PLANEH.

  AD IMENSIONS DAND E1 ARE MEASURED AT DATUM PLANEH.

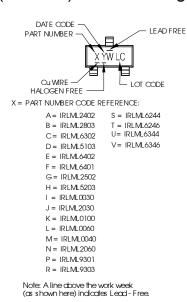
  DIMENSIONS DAND E1 ARE MEASURED AT DATUM PLANEH. DIMENSIONS DOES

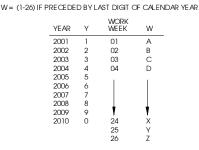
  NOT INCLUDE MOLD PHOTRUSIONS OR INTERLEAD FLASH. MOLD PROTRUSIONS. OR INTERLEAD FLASH SHALL NOT EXCEED 0.25 MM (0.010 INCH) PER SIDE.

  DIMENSION L IS THE LEAD LENGTH FOR SOLDERING TO A SUBSTRATE.

  8. OUTLINE CONFORMS TO JEDEC OUTLINE TO 236 AB.

#### Micro3™(SOT-23) Part Marking Information





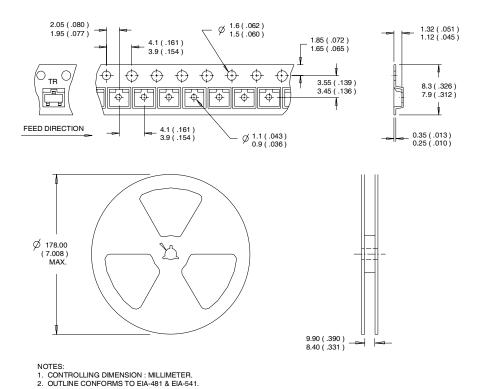
W= (27-52) IF PRECEDED BY ALETTER

YEAR	Υ	WORK WEEK	W
2001	Α	27	Α
2002	В	28	В
2003	С	29	С
2004	D	30	D
2005	E		
2006	F		
2007	G		
2008	Н	1	1
2009	J	7	1
2010	K	50	X
		51	Υ
		52	Z

Note: For the most current drawing please refer to IR website at: http://www.irf.com/package/

#### Micro3<sup>™</sup>(SOT-23) Tape & Reel Information

Dimensions are shown in millimeters (inches)



Note: For the most current drawing please refer to IR website at: <a href="http://www.irf.com/package/">http://www.irf.com/package/</a>



Orderable part number	Package Type	Standard Pack		Note
		Form	Quantity	
IRLML6344TRPbF	Micro3™(SOT-23)	Tape and Reel	3000	

#### Qualification information<sup>†</sup>

Ovelification level	Consumer <sup>††</sup>		
Qualification level	(per JEDEC JESD47F <sup>†††</sup> guidelines)		
Maiatura Caraitiritud aval	Minus CIM/COT 00)	MSL1	
Moisture Sensitivity Level	Micro3™(SOT-23)	(per IPC/JEDEC J-STD-020D <sup>†††</sup> )	
RoHS compliant	Yes		

- † Qualification standards can be found at International Rectifier's web site http://www.irf.com/product-info/reliability
- †† Higher qualification ratings may be available should the user have such requirements. Please contact your International Rectifier sales representative for further information: http://www.irf.com/whoto-call/salesrep/
- ††† Applicable version of JEDEC standard at the time of product release.

#### Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Pulse width  $\leq$  400 $\mu$ s; duty cycle  $\leq$  2%.
- 3 Surface mounted on 1 in square Cu board
- Refer to <u>application note #AN-994.</u>

Data and specifications subject to change without notice.



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TAC Fax: (310) 252-7903

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